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Time: 15:03:51

Inventor Name Search Result

Your Search was:

Last Name = LEE

First Name = CHENG-YIN

| Application# | Patent# | Status | Date Filed | Title | Inventor Name |
|--------------------------|-------------------------|--------|------------|--|----------------|
| 09588533 | 6879594 | 150 | 06/07/2000 | SYSTEM AND METHOD FOR LOOP AVOIDANCE IN MULTI-PROTOCOL LABEL SWITCHING | LEE, CHENG-YIN |
| 09753069 | 6915325 | 150 | 01/02/2001 | METHOD AND PROGRAM CODE FOR COMMUNICATING WITH A MOBILE NODE THROUGH TUNNELS | LEE, CHENG-YIN |
| 10226050 | Not Issued | 93 | 08/23/2002 | EXTENSIBLE OAM SUPPORT IN MPLS/ATM NETWORKS | LEE, CHENG-YIN |
| 10230294 | Not Issued | 161 | 08/29/2002 | Scalable path protection for meshed networks | LEE, CHENG-YIN |
| 10369567 | Not Issued | 61 | 02/21/2003 | Prohibit or avoid route mechanism for path setup | LEE, CHENG-YIN |
| 10369568 | Not Issued | 41 | 02/21/2003 | Customer site bridged emulated LAN services via provider provisioned connections | LEE, CHENG-YIN |
| 10604791 | Not Issued | 161 | 08/18/2003 | [SEMICONDUCTOR PACKAGE MODULE AND MANUFACTURING METHOD THEREOF] | LEE, CHENG-YIN |
| 10657230 | 6815833 | 150 | 09/09/2003 | FLIP CHIP PACKAGE | LEE, CHENG-YIN |
| 10664981 | Not Issued | 161 | 09/22/2003 | Semiconductor package with thermal enhance film and manufacturing method thereof | LEE, CHENG-YIN |
| 10690743 | Not Issued | 161 | 10/23/2003 | System in package structure | LEE, CHENG-YIN |
| 10724775 | Not Issued | 30 | 12/02/2003 | Hybrid virtual private LAN extensions | LEE, CHENG-YIN |
| 10796968 | Not Issued | 30 | 03/11/2004 | Ethernet path verification | LEE, CHENG-YIN |
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|-----------------|----------------|-----|------------|--|----------------|
| <u>10868496</u> | <u>7122757</u> | 150 | 06/14/2004 | CONTACT SENSOR PACKAGE STRUCTURE | LEE, CHENG-YIN |
| <u>10904574</u> | <u>7061079</u> | 150 | 11/17/2004 | CHIP PACKAGE STRUCTURE AND MANUFACTURING METHOD THEREOF | LEE, CHENG-YIN |
| <u>10907561</u> | Not Issued | 161 | 04/06/2005 | SEMICONDUCTOR PACKAGE MODULE AND MANUFACTURING METHOD THEREOF | LEE, CHENG-YIN |
| <u>10911692</u> | Not Issued | 30 | 08/05/2004 | Method for forwarding traffic having a predetermined category of transmission service in a connectionless communications network | LEE, CHENG-YIN |
| <u>10934409</u> | <u>7187070</u> | 150 | 09/07/2004 | STACKED PACKAGE MODULE | LEE, CHENG-YIN |
| <u>11009917</u> | Not Issued | 30 | 12/10/2004 | Virtual private network connection methods and systems | LEE, CHENG-YIN |
| <u>11020437</u> | Not Issued | 30 | 12/22/2004 | Virtual private networking methods and systems | LEE, CHENG-YIN |
| <u>11020503</u> | Not Issued | 30 | 12/23/2004 | Method and apparatus for configuring a communication path | LEE, CHENG-YIN |
| <u>11058274</u> | Not Issued | 30 | 02/16/2005 | IP to VPLS interworking | LEE, CHENG-YIN |
| <u>11210700</u> | Not Issued | 61 | 08/25/2005 | Method for stacking BGA packages and structure from the same | LEE, CHENG-YIN |
| <u>11224057</u> | Not Issued | 30 | 09/13/2005 | Low latency working VPLS | LEE, CHENG-YIN |
| <u>11306818</u> | Not Issued | 30 | 01/12/2006 | MULTI-CHIP PACKAGE STRUCTURE | LEE, CHENG-YIN |
| <u>11332293</u> | Not Issued | 71 | 01/17/2006 | Multi-chip package structure | LEE, CHENG-YIN |
| <u>11420230</u> | Not Issued | 30 | 05/25/2006 | SYSTEM-IN-PACKAGE STRUCTURE | LEE, CHENG-YIN |
| <u>11463404</u> | Not Issued | 30 | 08/09/2006 | CHIP PACKAGE STRUCTURE | LEE, CHENG-YIN |
| <u>11505325</u> | Not Issued | 30 | 08/17/2006 | Die package and method for making the same | LEE, CHENG-YIN |
| <u>11520769</u> | Not Issued | 30 | 09/14/2006 | Multi-chip package structure | LEE, CHENG-YIN |
| <u>11634059</u> | Not Issued | 30 | 12/06/2006 | Substrate structure having a solder mask and a process for making the | LEE, CHENG-YIN |

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| | | | | same | |
| <u>11636975</u> | Not Issued | 30 | 12/12/2006 | Stackable semiconductor package | LEE, CHENG-YIN |
| <u>11636986</u> | Not Issued | 30 | 12/12/2006 | Stackable semiconductor package | LEE, CHENG-YIN |
| <u>11636993</u> | Not Issued | 30 | 12/12/2006 | Stackable semiconductor package | LEE, CHENG-YIN |
| <u>11637786</u> | Not Issued | 30 | 12/13/2006 | Manufacturing method of a package structure | LEE, CHENG-YIN |
| <u>11744189</u> | Not Issued | 17 | 05/03/2007 | Semiconductor package | LEE, CHENG-YIN |
| <u>11828351</u> | Not Issued | 17 | 07/26/2007 | Semiconductor package and semiconductor device | LEE, CHENG-YIN |
| <u>11828352</u> | Not Issued | 17 | 07/26/2007 | Method of making a semiconductor package and method of making a semiconductor device | LEE, CHENG-YIN |
| <u>60137717</u> | Not Issued | 159 | 06/07/1999 | METHOD FOR AVOIDING LOOPS IN MPLS | LEE, CHENG-YIN |
| <u>60188811</u> | Not Issued | 159 | 03/13/2000 | Apparatus and method of communicating between a mobile network device and a correspondent network device | LEE, CHENG-YIN |

Inventor Search Completed: No Records to Display.

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|---------------------------------|----------------------------------|--|---------------------------------------|
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